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U.S. Patent Application Serial No. 10/646,922
Response to OA dated October 29, 2008

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (Cancel)

Claim 2 (Currently Amended): A foldable electronic device comprising:
a main body (1),
a closure (2),
a main display (4),
a subdisplay (5),
a frame (6),
a chip mount area (42) of a flexible lead (41) extending from the main display (4), and
a chip mount area (53) of a flexible lead (51) extending from the subdisplay (5),
the main body and the closure being connected to each other operably, the main display having a screen exposed from an inner surface of the closure (2), the subdisplay (5) having a screen exposed from a back surface of the closure (2), the frame (6) being provided inside the closure (2) and holding therein the main display (4) and the subdisplay (5) as arranged back to back, the chip mount area (42) and the chip mount area (53) being opposed to each other in an opening formed in the frame (6), the opposed surfaces of the respective chip mount areas (42), (53) having at least one

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portion with a group of electronic circuit chips (43)(54) mounted thereon and at least one portion free of a group of electronic circuit chips,

wherein the at least one portion of the chip mount area (42) of the flexible lead (41) having a group of electronic circuit chips (43) opposes the at least one portion of the chip mount area (53) free of a group of electronic circuit chips,

the at least one portion of the chip mount area (53) of the flexible lead (51) having a group of electronic circuit chips (54) opposes the at least one portion of the chip mount area (42) free of a group of electronic circuit chips, and

the flexible lead (51) extending from the subdisplay (5) has an outer end portion folded over toward the frame (6) side, and the folded-over portion has a surface opposed to the frame (6) and providing the chip mount area (53),

wherein the frame (6) has said opening in a second area thereof adjacent to a first area thereof covered with the subdisplay (5), and the flexible lead (51) extending from the subdisplay (5) is folded over on the second area,

wherein the flexible lead (41) extending from the main display (4) is folded over toward the frame (6) side, and the folded-over lead portion has a surface opposed to the frame (6) and providing the chip mount area (42), and

wherein the electronic circuit chips (54) in the chip mount area (53) of the flexible lead (51) extending from the subdisplay (5) and the electronic circuit chips (43) in the chip mount area (42) of the flexible lead (41) extending from the main display (4) are positioned in a staggered meshing

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relation within said opening of the frame (6), and

wherein frame (6) is disposed between flexible lead (41) and flexible lead (51) with
electronic circuit chips (54) and electronic circuit chips (43) extending through said opening in said
frame (6) to mesh absent any component of said foldable electronic device; arranged between said
electronic circuit chips (54) and said electronic circuit chips (43).

Claims 3-7 (Cancelled)